PCN Number:		20	20140523000A PCN Date: 07/01/20					014							
Title	Qualification Block Device		Red	uced Wire	Bor	nd diam	eter for th	e Fa	m	ily of	Discrete	e Clip	& Pov	ver	
Customer Contact:		<u>PCN</u>	N Ma	inager	F	Phone:	<b>he:</b> +1(214)480-6037			)37	Dept:		ality vices		
Prop	Proposed 1 <sup>st</sup> Ship Da			10/01/201	4	Estim	stimated Sample Availability			bility:		e prov n requ			
Char	nge Type:							-							
	Assembly Site		Assembly Process Assembly Materia												
	Design		Electrical Specification   Mechanical Specification     Packing/Shipping/Labeling   Test Process				icatio	n							
	Test Site Wafer Bump Site		$\square$	Wafer B				╂╞	╡┤		st Process Ifer Bump Process				
	Wafer Fab Site		$\square$	Wafer Fa				┼┝	╡╂		er Fab Pr				
				Part nun									-		
					Ρ	CN De	etails								
Desc	cription of Chang	je:													
<mark>expe</mark> newl Texa	Revision A is to announce the <u>addition</u> of new devices that were not included on the original PCN notification. These new devices are highlighted and <b>bolded</b> in the device list below. The expected first shipment date for these new devices will be 90 days from this notice for these newly added devices only. Texas Instruments is pleased to announce the qualification a reduced bond wire diameter for the family of Discrete Clip & Power Block Devices:						ne								
Current New															
Bond Wire		e/Di	/Diameter						Δ	Au, 1.0 mil					
Reason for Change:											u/ 110 11				
Reas	son for Change:					7107	2.0 mm				<u>u, 10 ii</u>				
	son for Change: inuity of Supply						2.0 mm								
Cont		on Fi	it, I	Form, Fui	ncti			elia	bi				egativ	/e):	
Cont	inuity of Supply cipated impact c	on F	it, I	Form, Fui	ncti			elia	bil				egativ	/e):	
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Cont Antio	inuity of Supply cipated impact o e nges to product			•		ion, Qu	ality or R		bil				egativ	/e):	
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Cont Antie None Char None Prod	inuity of Supply cipated impact of a nges to product	ider	ntif	•		ion, Qu	ality or R	CN:	bi	lity (		e / ne	egativ	/e):	
Cont Antia None Char None Prod	inuity of Supply cipated impact of a nges to product a luct Affected	ider CS	ntif	ication re		ion, Qu Iting fro	ality or R om this P	CN:	bil	lity (	positive	<b>e / ne</b> 5Q5D	egativ	/e):	
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CSD16401Q5	CSD17309Q3	CSD18540Q5B	CSD87351ZQ5D	
CSD16406Q3	CSD17311Q5	CSD19502Q5B	CSD87352Q5D	
CSD16407Q5	CSD17312Q5	CSD19532Q5B	CSD87353Q5D	
CSD16407Q5C				

Qualification Data – Approved May, 2014							
This qualification has been specifically developed for the validation of this change. The qualification data							
validates that the pro	validates that the proposed change meets the applicable released technical specifications.						
Reference Qualification# 1 : CSD87331Q3D (MSL 1-260C)							
Package Construction Details							
Assembly Site:	PAC	Mold Compound:	SID#200805				
# Pins-Designator, Family:	8-DQZ, LSON-CLIP	Mount Solder:	SID#200757				
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au				
Qualification: 🗌 Plan 🛛 Test Results							
Reliability Test	Conditions	Conditions					
**T/C -40C/125C	-40C/+125C (500	-40C/+125C (500 Cyc)					
Notes **- Preconditioning sequence: Level 1-260C.							

Qualification Data – Approved May, 2014							
This qualification has been specifically developed for the validation of this change. The qualification data							
validates that the pro	validates that the proposed change meets the applicable released technical specifications.						
Reference Qualification# 2 : CSD58869Q5D (MSL 1-260C)							
Package Construction Details							
Assembly Site:	PAC	Mold Compound:	SID#202828				
# Pins-Designator, Family:	8-DQY, LSON-CLIP	Mount Solder:	SID#200757				
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au				
Qualification: 🗌 Plan 🛛 Test Results							
Reliability Test	Conditions	Conditions					
**T/C -40C/125C	-40C/+125C (500	-40C/+125C (500 Cyc)					
Notes **- Preconditioning sequence: Level 1-260C.							

Qualification Data – Approved May, 2014							
This qualification has been specifically developed for the validation of this change. The qualification data							
validates that the proposed change meets the applicable released technical specifications.							
Reference Qualification# 3 : CSD16407Q5 (MSL 1-260C)							
Package Construction Details							
Assembly Site:	PAC	Mold Compound:	SID#202828				
# Pins-Designator, Family:	8-DQH, LSON-CLIP	Mount Solder:	SID#200757				
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au				
Qualification: 🗌 Plan 🛛 Test Results							
Reliability Test	Conditions	Conditions					
**T/C -40C/125C	-40C/+125C (500	-40C/+125C (500 Cyc)					
Notes **- Preconditioning sequence: Level 1-260C.							

Qualification Data – Approved May, 2014							
This qualification has been specifically developed for the validation of this change. The qualification data							
validates that the proposed change meets the applicable released technical specifications.							
Reference Qualification# 4 : CSD25401Q3 (MSL 1-260C)							
Package Construction Details							
Assembly Site:	PAC	AC Mold Compound:					
# Pins-Designator, Family:	8-DQG, LSON-CLIP	Mount Solder:	SID#200757				
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au				
Qualification: 🗌 Plan 🛛 Test Results							
Reliability Test	Conditions	Conditions					
**T/C -40C/125C	-40C/+125C (500	-40C/+125C (500 Cyc)					
Notes **- Preconditioning sequence: Level 1-260C.							

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com